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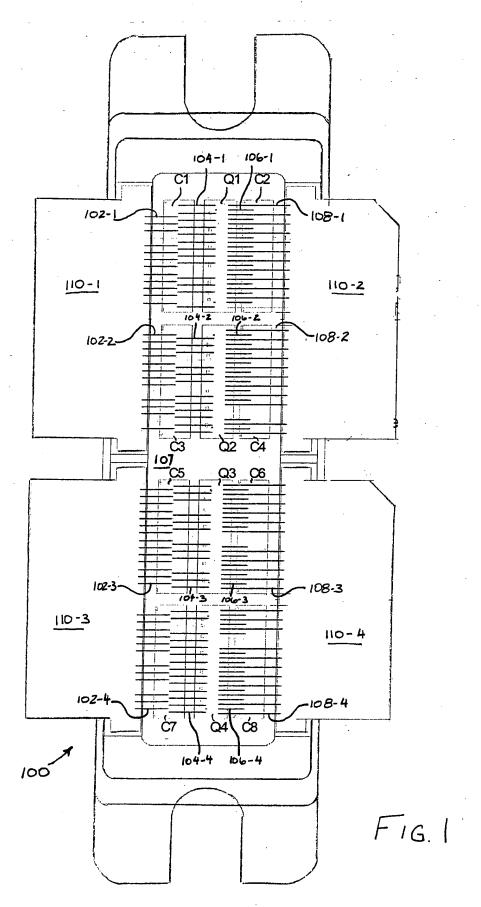
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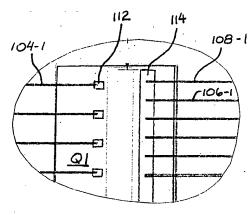
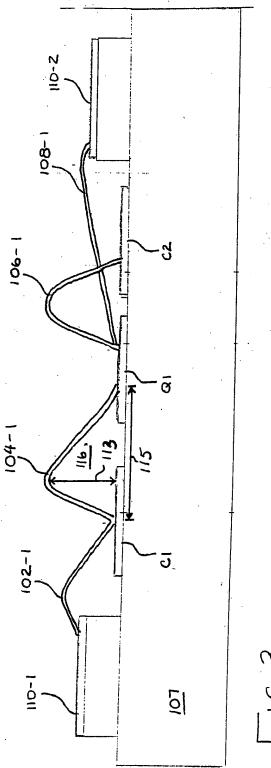
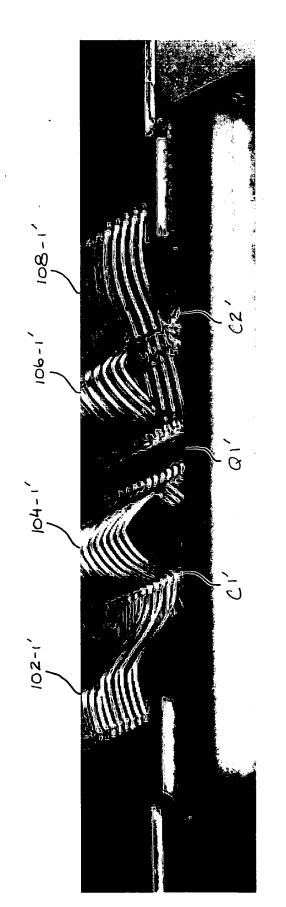


Fig. 2



T 16. (2)



F1G. 4

502 Align first bond site in the bonding tool and measure selected bond distances each corresponding to one of a plurality of wire bonds to be formed 504 Calculate an average of the bond distances 506 Calculate a target area under a hypothetical wire bond profile from the average bond distance, using a baseline wire length and a baseline loop height 508 Begin wire bonding process For a given one of the wire bonds to be formed 510 calculate an area under a hypothetical wire bond profile from the corresponding one of the measured bond distances, using the baseline wire length and the baseline loop height Compare the calculated area for the measured 512 bond distance to the target area If the calculated area differs from the target area 514 by more than a designated amount, form the given wire bond using an adjusted wire length so that the area under the wire bond profile for the given wire bond is substantially equal to the target area, and otherwise form the given wire bond using the baseline wire length 516 Repeat steps 510, 512 and 514 for each of the remaining wire bonds to be formed

